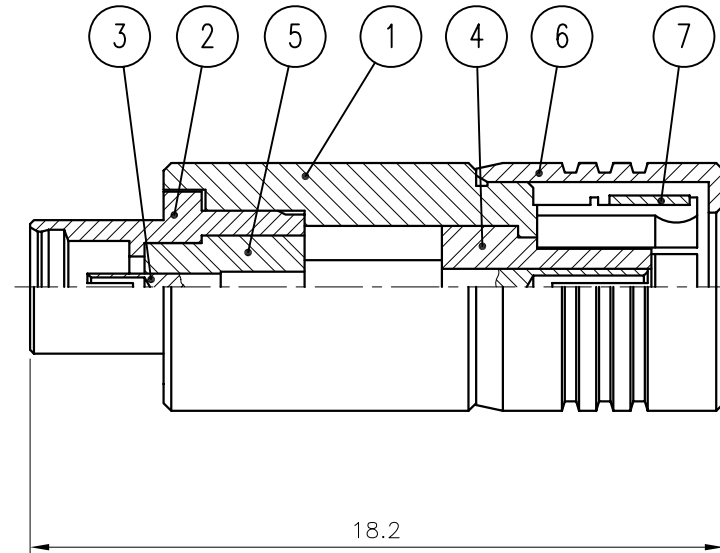


REVISION				
REV	DESCRIPTION	DRAWN	APPR	DATE
IR	Initial Registration	G.Y.KIM	I.C.KIM	2016.11.25.
1	[설번처리 No.201612-0028] 상대물 결합 텐션 약하게 변경	G.Y.KIM	I.C.KIM	2016.12.28.
2	도금사양 변경 (Gold->Nickel) 영업 요청	I.C.KIM		2017.02.20.



Electrical spec

1. Insertion Loss: 0.2dB @ DC~3Ghz

*조립방법

1. ①번 BODY(A)에 ④번 TEFLON을 조립한다.
2. ②번 BODY(B)에 ⑤번 TEFLON을 조립한다.
3. ①번 BODY(A)에 ③번 PIN을 조립하고 ②번 BODY(B)를 억지끼움 한다.
4. ⑦번 SPRING RING을 조립한다.
5. ⑥번 CAP을 ①번 BODY(A)에 억지끼움 한다.

1	7	SPRING RING	1	BeCu C17300	Copper Plate	DSR00009-5/1 DSR00004-5/1
2	6	COUPLING CAP	1	MBsBD C3604BD-F	Nickel Plate	DCU00021-5/3
	5	INSULATOR	1	TEFLON		DIN02852-N/1
	4	INSULATOR	1	TEFLON		DIN02851-N/1
	3	CONTACT	1	BeCu C17300	Gold Plate	DAC03264-5/1
2	2	BODY(B)	1	MBsBD C3604BD-F	Nickel Plate	DBD02161-5/2
2	1	BODY(A)	1	MBsBD C3604BD-F	Nickel Plate	DBD04257-5/2
	NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE

TOLERANCE	Decimal	DATE 2017. 02. 20.		 RF & MICROWAVE TECHNOLOGY Tel : 82-32-347-8015 Fax : 82-32-347-8017
	Angle	APPROVED BY		
MATERIAL		CHECKED BY		KJ COMTECH CO.,LTD. TITLE MMCX50 (J) SMB50 (P) ST Adaptor
		DRAWN BY	I.C.KIM	
FINISH	-	SCALE	5/1	DWG NO. AD00596-7/1
		UNIT	mm	REVISION 2
				SHEET 1 of 1